

ON Semiconductor				10/15/2019	
Base Part		NC7WZ241	HF	Pb-free	
Orderable Part		NC7WZ241K8X	Total weight (mg)		9.554
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight	
Die	0.16	Silicon (Si)	7440-21-3	100	
Die Attach	0.14	Silver (Ag)	7440-22-4	75	
		Phenolic Resin-2	54208-63-8	25	
Lead Frame	4.286	Silver (Ag)	7440-22-4	6.18292114	
		Zinc (Zn)	7440-66-6	0.18665422	
		Iron (Fe)	7439-89-6	2.26318245	
		Copper (Cu)	7440-50-8	91.22725152	
		Phosphorus (P)	7723-14-0	0.13999067	
Mold Compound-Black	4.768	Ortho Cresol Novolac Resin	29690-82-2	20.00838926	
		Carbon Black (C)	1333-86-4	0.5033557	
		Fused Silica (SiO2)	60676-86-0	79.48825503	
Plating	0.15	Tin (Sn)	7440-31-5	100	
Wire Bond - Au	0.05	Gold (Au)	7440-57-5	100	
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>					